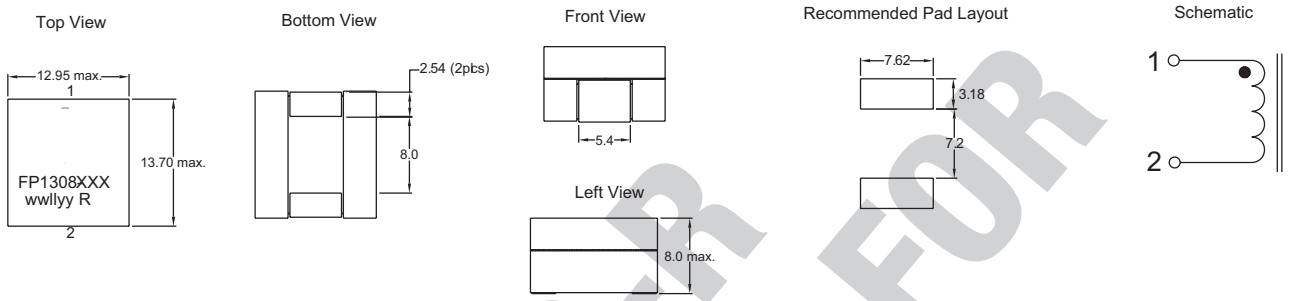
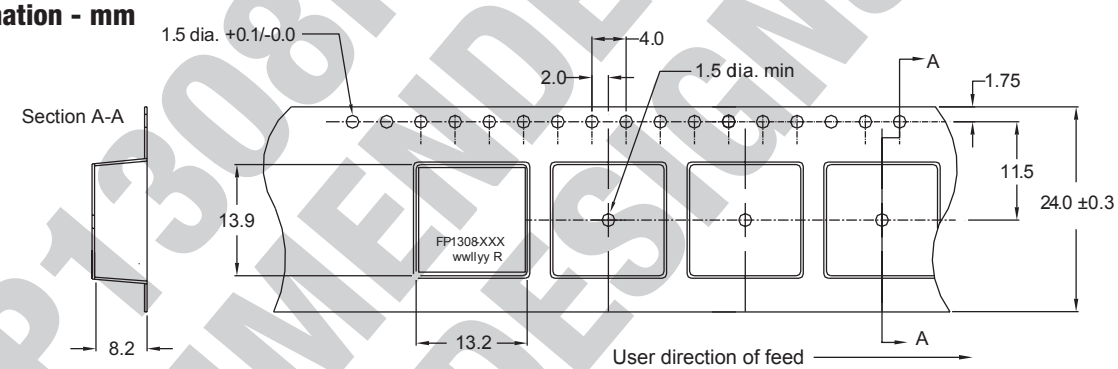
Dimensions - mm



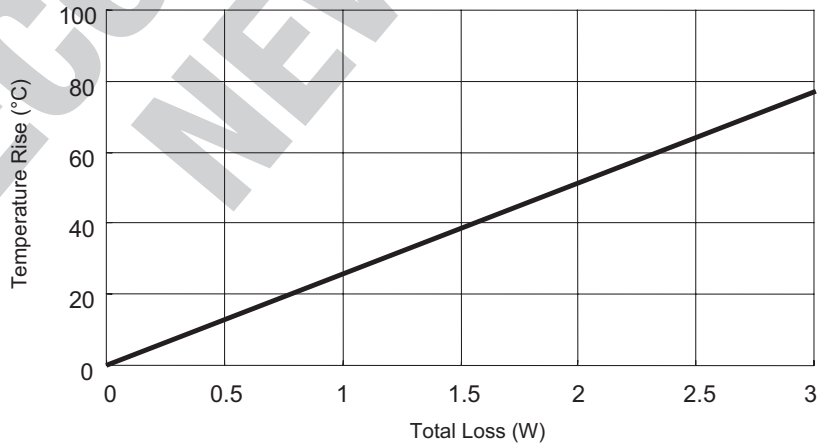
Part Marking: FP1308 xxx = Inductance value in µH. (R = Decimal point). If no "R" is present, then last character is # 0f zeros wwllyy = Date code R = Revision level

Packaging Information - mm

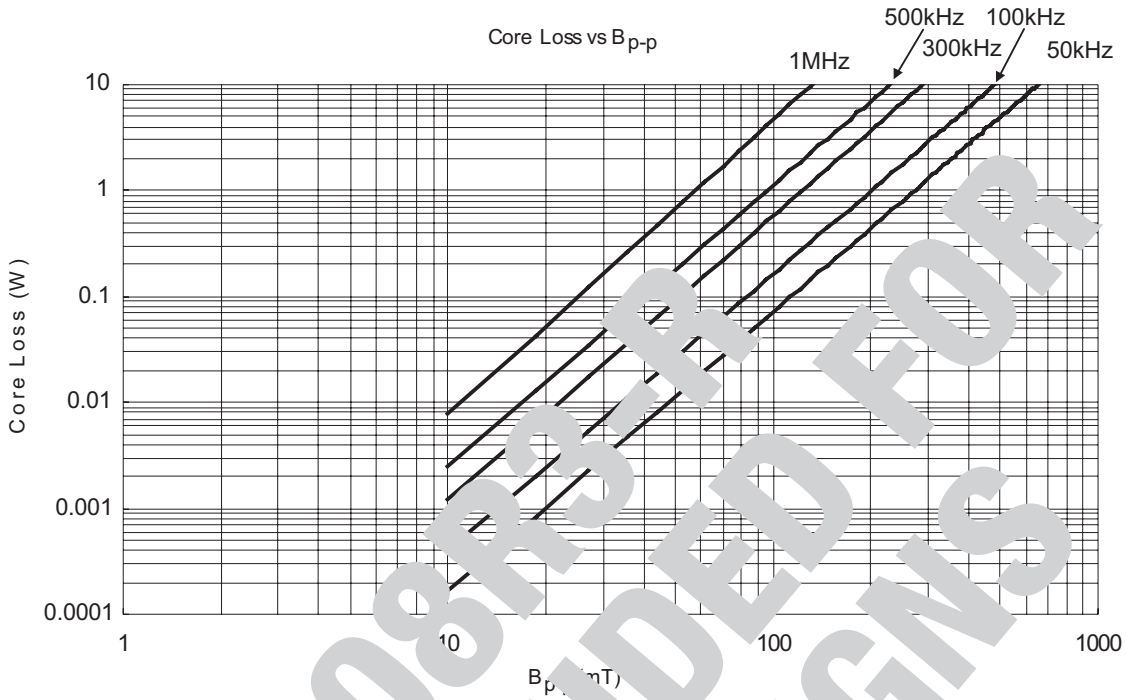


Supplied in tape-and-reel packaging, 400 parts per reel, 13" diameter reel.

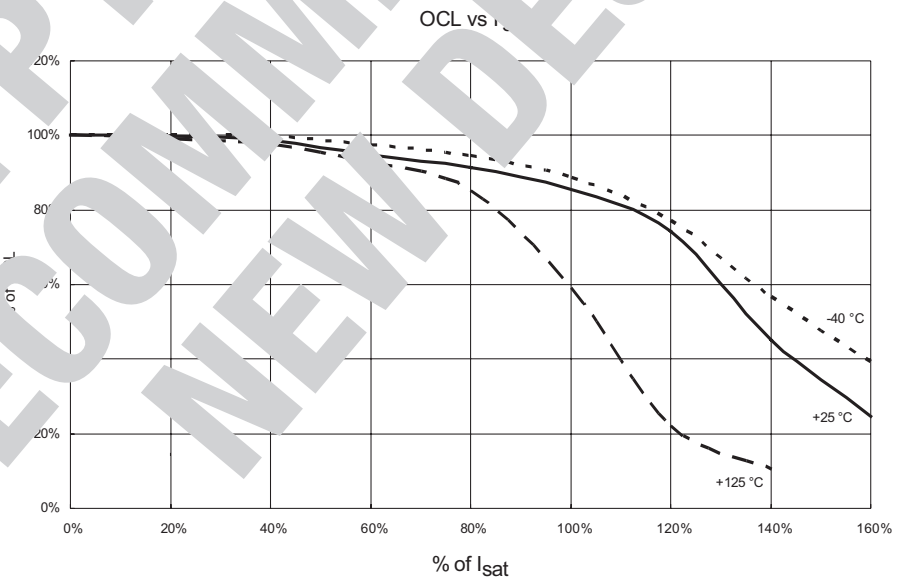
Temperature Rise vs. Total Loss



Core Loss



Inductance Characterist



Solder Reflow Profile

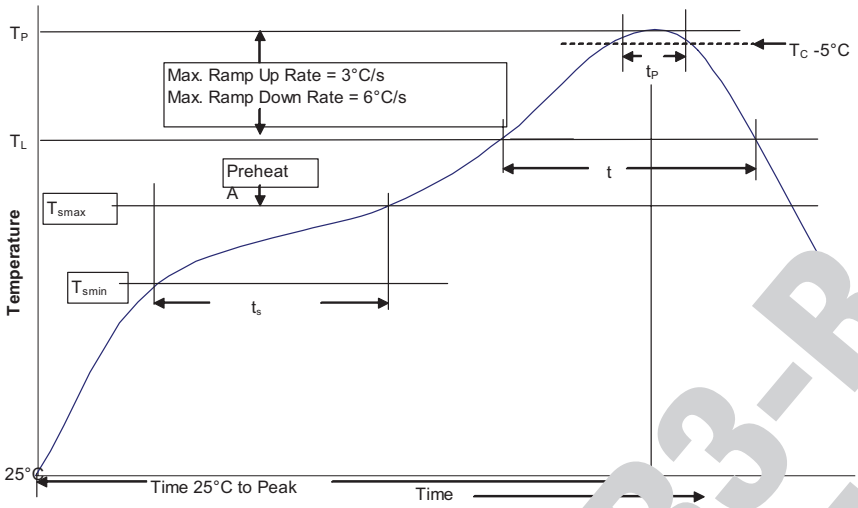


Table 1 - Standard SnPb Solder (T_C)

Package Thickness	Volume mm³ <350	Volume mm³ ≥350
<2.5mm	235°C	0°C
≥2.5mm	220°C	

Table 2 - Lead [illegible] (T_C)

Package Thick[illegible]s	[illegible]ume [illegible] 350	Volume mm³ 350 - 2000	Volume mm³ >2000
<1.6mm	260°C	260°C	260°C
1.6 – 2.5mm	0°C	250°C	245°C
2.5mm	2[illegible]°C	245°C	245°C

Reference JDEC J-STD-020

Profile Feature		[illegible]d SnPb Solder	[illegible]Free Solder
Preheat and Soak	• Temperature min. (T_{sm}	00°C	150°C
	• Temperature max. (T_{s} [illegible]x)	50°C	200°C
	• Time (T_{smin} to [illegible])	60 120 Se[illegible]ds	60-120 Seconds
Average ramp up rate T_{smax} to T_p		°C/ Sec[illegible]d M[illegible]	3°C/ Second Max.
Liquidous temperature (T_L) Time at liquidous (t_L)		3°C 60 15[illegible]onds	217°C 60-150 Seconds
Peak package body temperature (T_P)*		Table 1	Table 2
Time (t_p)** within 5 °C of the [illegible]ied classification [illegible]pe[illegible]tu[illegible] (T_C)		[illegible]econ[illegible]s**	30 Seconds**
Average ramp-down rate (T_p [illegible]max)		°C/ [illegible]d Max.	6°C/ Second Max.
Time 25°C to Peak Te[illegible]pera[illegible]ure		[illegible]nutes Max.	8 Minutes Max.

* Tolerance for peak prof[illegible]mperature (T_p) is [illegible]ed as a [illegible]olier minimum and a [illegible]aximum.

** Tolerance for time at peak p[illegible]e temperature [illegible]s [illegible]d as a suppl[illegible] minimum and a user maximum.

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